



## About STATS ChipPAC

STATS ChipPAC (SGX-ST: STATSchP) is a leading service provider of semiconductor packaging design, bump, probe, assembly, test and distribution solutions. We have the scale to provide a comprehensive range of semiconductor packaging and test solutions to a diversified global customer base servicing the computing, communications and consumer markets.

## Technology and Services

With a broad technology portfolio ranging from leadframe to laminate, flip chip, wafer level and advanced 3D packaging solutions, STATS ChipPAC provides innovative and cost effective semiconductor solutions. STATS ChipPAC has a leadership position in advanced package technology including fan-in and fan-out wafer-level packaging, flip chip interconnect, 3D integration and Through Silicon Via (TSV) to meet the increasing market demand for next-generation devices with higher levels of integration, increased functionality and compact sizes.

As a full turnkey service provider, STATS ChipPAC provides wafer probe and final testing on a diverse selection of testers covering the major test platforms in the industry and has proven expertise in testing a broad range of semiconductors, especially mixed-signal, radio frequency (RF), analog and high-performance digital devices.



## Business Highlights

### Operations

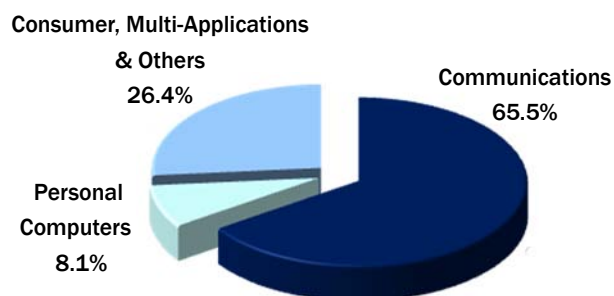
STATS ChipPAC's manufacturing facilities are located in strategic semiconductor markets including South Korea, Singapore, China and Taiwan. Our close proximity to the major hubs of wafer fabrication allows us to provide customers with fully-integrated, multi-site packaging and test services.

We market our services through a direct sales force and customer support teams in the United States, Singapore, South Korea, China, Taiwan and Switzerland.

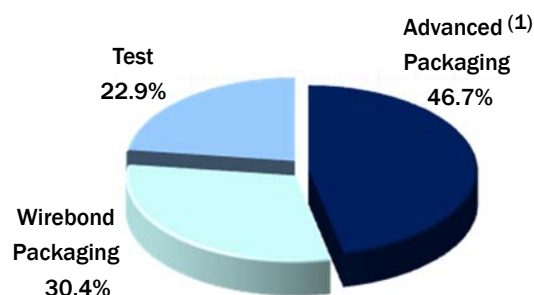


Note: 3,682 wire bonders and 968 testers as of 3Q 2014

### 3Q 2014 Revenue by End User Market



### 3Q 2014 Revenue by Product Line



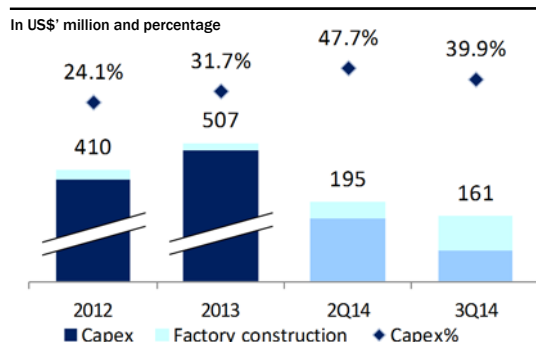
(1) Advanced Packaging includes flip chip and wafer level packaging.

## Financial Highlights

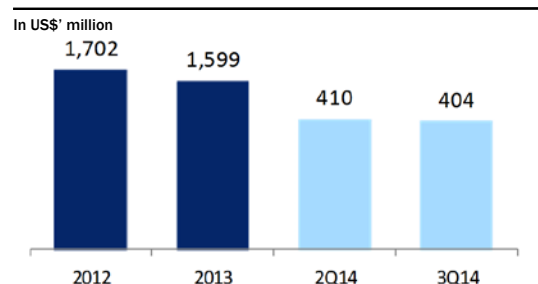
### 3Q 2014 Financial Results

- 3Q 2014 revenue decreased by 1.5% over prior quarter and increased 0.7% over 3Q 2013
- Wafer supply delays at several key customers and demand shift from high-end smartphones toward the low-cost smartphone segment impacted revenue
- New business ramp for advanced packaging programs and seasonal strength in the consumer segment helped to partially offset weakness in our wireless communication revenue

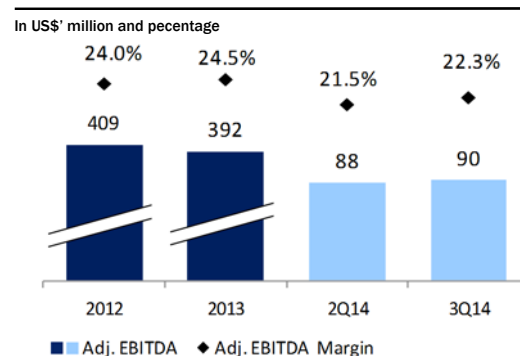
#### Capex and Capex as % of Revenue



#### Revenue



#### Adjusted Earnings Before Interest, Taxes, Depreciation and Amortization (EBITDA)<sup>(1)</sup>



Note: (1) Adjusted EBITDA is defined as net income attributable to STATS ChipPAC Ltd. plus income tax expense, interest expense, net, depreciation and amortisation, restructuring charges, share-based compensation, goodwill and equipment impairment, tender offer, debt exchange or debt redemption expenses and write-off of debt issuance costs. Adjusted EBITDA excludes the plant closure costs related to our Malaysia plant and our restructuring actions.

## Recent Headlines

- 20 Aug 14 STATS ChipPAC's fcCuBE® Technology Surpasses 100 Million Unit Milestone
- 6 Aug 14 STATS ChipPAC Honours Top Suppliers for Excellent Performance and Outstanding Support
- 29 Jul 14 STATS ChipPAC's Encapsulated Wafer Level Chip Scale Package (eWLCSP™) Delivers Superior Quality Results
- 28 May 14 STATS ChipPAC Introduces Robust Encapsulated Wafer Level Packaging Technology

## Corporate Information

### Executive Management

Tan Lay Koon, Director, President and Chief Executive Officer  
 Dr. Han Byung Joon, Executive VP and Chief Technology Officer  
 Hal Lasky, Executive VP and Chief Sales Officer  
 Raymond Quek, Senior VP and Co-Chief Sales Officer  
 Dennis Chia Choon Hwee, Senior VP and Chief Financial Officer  
 Janet Taylor, Senior VP, General Counsel and Company Secretary

### Investor Relations Contact

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### Corporate Headquarters

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### Stock Information

Singapore Exchange Securities  
 Trading Limited (SGX-ST)  
 Ticker: STATSchP

